Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6251774".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:27
L2	24837	(etch$3 or pattern$3 or remov$3) near25 (water$3 near3 acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:28
L3	23240	(etch$3 or pattern$3 or remov$3) near15 (water$3 near3 acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:28
L4	1104	(etch$3 or pattern$3 or remov$3) near15 (substrate or wafer) near15 (water$3 near3 acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:28
L5	687	(etch$3) near15 (substrate or wafer) near15 (water$3 near3 acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:29
L6	2	(etch$3) near15 (substrate or wafer) near15 (watery near acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:29
L7	2	(etch$3) near15 (substrate or wafer) near15 (chemical$3 near3 watery near acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:30
L8	1	(remov$3) near15 (substrate or wafer) near15 (chemical$3 near3 watery near acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:30
L9	1	(pattern$3) near15 (substrate or wafer) near15 (chemical$3 near3 watery near acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:39

L10	2	"6121123".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:47
L11	2	"6004843".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/01 21:48